

2T32X5YX0003HSAA

Ultra high reliability and luminous efficacy ,PLCC LED Series are optimized to be used as lighting for automotive signal lighting designs or signboard.





I Applications:

- Automotive Interior/Exterior Lighting
- Traffic Lighting

— Signal Lighting

I Features:

- Package: Ag Plated 3 pad design package with silicone resin
- Dimension: 4.0 mmx4.3 mmx2.75 mm
- Chip technology: AlGaInP
- View Angle: 120°
- Color: λ_{dom} =592nm(Yellow)
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- MSL: Level 2
- Qualifications: The product qualification test based on the guidelines of AEC-Q102



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General Information

Ordering Code Format

	X1		X2	2	X3-X4	X5	i-X6	X	7-X8
	Туре	Com	ponent	:	Series	Wat	ttage	Colo	or/CCT
2	Emitter	Т	PLCC	32	4043 Sideled	X5	0.5W	YX	Yellow

X9-X	(10	X11-	X12		X13)	X14		X15
CRI(I	Ra)	Volt	age	Leadfi	rame Mode	Leadfra	me Plating	1	Model
00	-	03	3V	Н	PPA Sideled 2.75H 3Pin	S	Silver	A	Automotive

X16 Serial Number

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Absolute Maximum Ratings

Absolute maximum ratings

Parameter		Symbol	Values
Operating Temperature	min. max.	T_{op}	-40 °C 110 °C
Storage Temperature	min. max.	T_{stg}	-40 °C 110 °C
Junction Temperature	max.	T_j	125 °C
Forward current T _J = 25 °C	min. max.	I _F	5 mA 200 mA
Surge Current $t \le 10 \mu s$; $D = 0.005$; $T_J = 25 ^{\circ}C$	max.	I _{FS}	300 mA
Reverse voltage $T_J = 25 ^{\circ}\text{C}$	max.	V_{R}	10 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)		V_{ESD}	2 kV

Notes: Proper current derating must be observed to maintain junction temperature below the maximum at all time.

Characteristics

 $I_F = 140 \text{ mA}; T_J = 25 \text{ °C}$

Parameter		Symbol	Values
Peak Wavelength	typ.	λ_{Peak}	595 nm
Dominant Wavelength	min. typ. max.	$\lambda_{\sf dom}$	589 nm 592 nm 595 nm
Viewing angle	typ.	φ	120°
Forward Voltage	min. typ. max.	$V_{\scriptscriptstyle F}$	2.05 V 2.15 V 2.35 V
Reverse current V _R = 10 V	typ. max.	I _R	0.01 μA 10 μA
Real thermal resistance junction/solder point	typ. max.	$R_{thJSreal}$	37 K / W 45 K / W
Electrical thermal resistance junction/ solder point with efficiency ηe = 14 %	typ. max.	$R_{\text{thJS elec.}}$	32 K / W 38 K / W



Luminous Intensity Characteristic

Luminous Intensity Characteristics, I_F=140mA , T_J=25°C

Symbol	Group	Min. Luminous Intensity(mcd)	Max. Luminous Intensity(mcd)	Typ. Luminous Flux(lm)
	DB	5600	7100	19.24
lv	EA	7100	9000	24.24
	EB	9000	11200	30.30

The luminous intensity performance is guaranteed within published operating conditions. Edison Opto maintains a tolerance of $\pm 10\%$ on intensity measurements.

Voltage Bin Structure

Voltage Bin Structure, $I_F=140mA$, $T_J=25^{\circ}C$

Symbol	Group	Min. Voltage (V)	Max. Voltage (V)
	B05	2.05	2.20
V _F	B20	2.20	2.35
	B35	2.35	2.50

Note:

Forward voltage measurement allowance is \pm 0.1V.

Wavelength Bin Structure

Wavelength Bin Structure, $I_{\scriptscriptstyle F}\!\!=\!140mA$, $T_{\scriptscriptstyle J}\!\!=\!\!25^{\circ}C$

Symbol	Group	Min. Wd (nm)	Max. Wd (nm)
,	A89	589	592
Λ _{dom}	A92	592	595

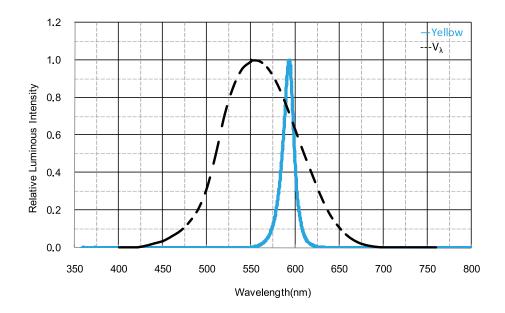
Dominant wavelength meansurement allowance is $\pm 1 \text{nm}$.



Characteristic Curves

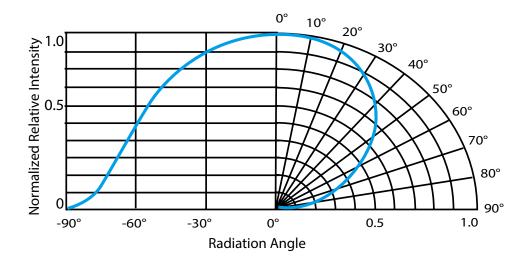
Color Spectrum

 $I_F = 140 \text{ mA} ; T_J = 25 \text{ °C}$



Beam Pattern

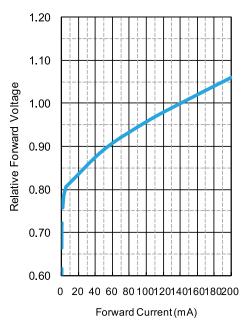
 $I_F = 140 \text{ mA}$; $T_J = 25 \,^{\circ}\text{C}$





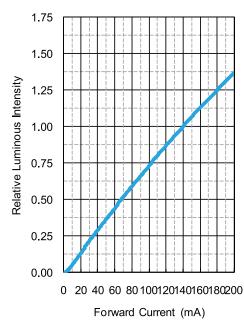
Relative Foward Voltage

 $V_F/V_F(140 \text{ mA}) = f(I_F); T_J = 25 \text{ °C}$



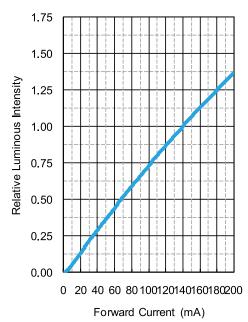
Relative Luminous Intensity

 $I_v/I_v(140 \text{ mA}) = f(I_F); T_J = 25 \text{ °C}$



Shift in Dominant Wavelength

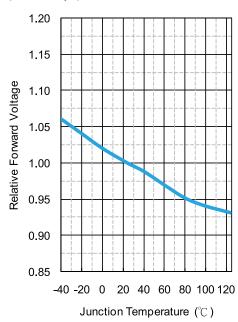
 $\Delta\lambda_{dom} = \!\! \lambda_{dom} \! - \!\! \lambda_{dom}$ (140 mA); $T_J = 25$ °C





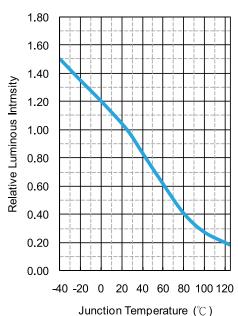
Relative Forward Voltage

 $V_F/V_F(25 \text{ °C}) = f(T_J); I_F = 140 \text{ mA}$



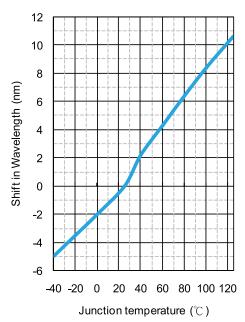
Relative Luminous Intensity

 $I_v/I_v(25 \text{ °C}) = f(T_J); I_F = 140 \text{ mA}$



Shift in Dominant Wavelength

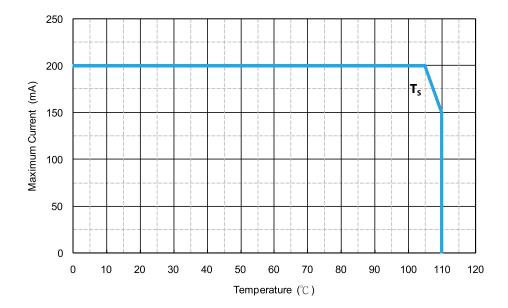
 $\Delta\lambda_{dom} = \!\! \lambda_{dom} \! - \!\! \lambda_{dom}$ (25 °C); $I_F = 140 \; mA$





Max. Permissible Forward Current

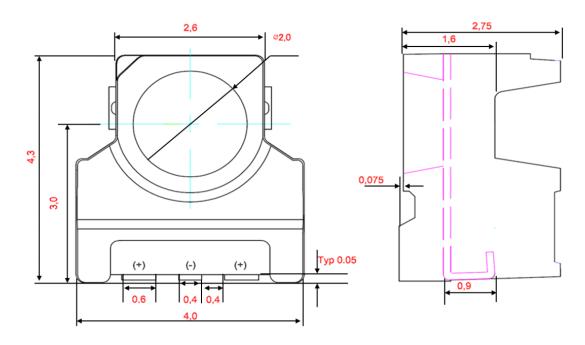
 $I_F = f(T)$



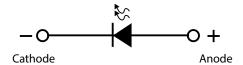


Mechanical Dimensions

Dimensional Drawing



Circuit



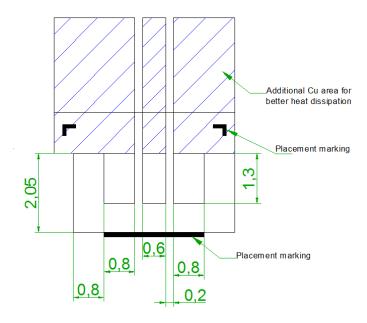
Emitting Center / Package Center

Notes:

- 1. All dimensions are measured in mm.
- 2. Tolerance: ± 0.1 mm
- 3. Approximate Weight: 47.0 mg



Recommended Solder Pad



Paddesign for improved heat dissipation



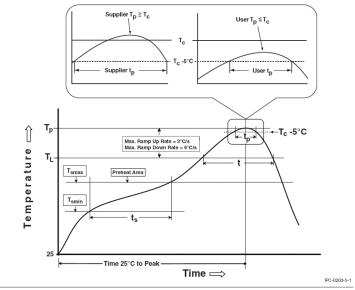
Notes:

- 1. All dimensions are measured in mm.
- 2. Tolerance: \pm 0.1 mm



Reflow Profile

The following reflow profile is from IPC/JEDEC J-STD-020D which provided here for reference.



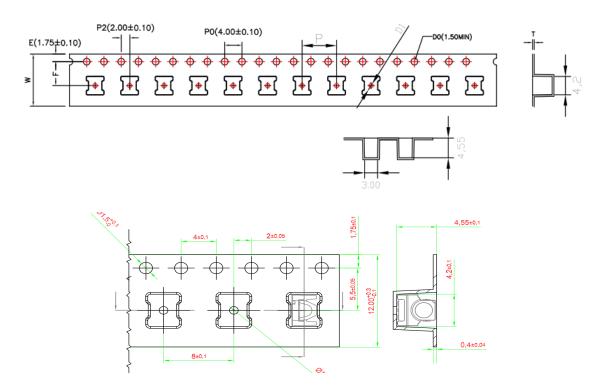
Reflow Profiles

Classification Reflow Profiles

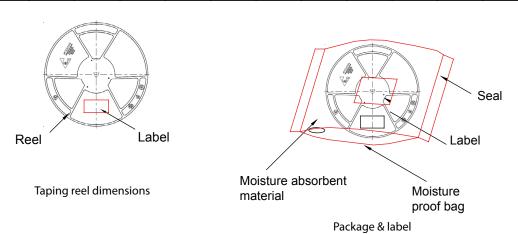
Profile Feature	Pb-Free Assembly
Preheat & Soak Temperature min (Tsmin) Temperature max (Tsmax) Time (Tsmin to Tsmax) (ts)	150 °C 200 °C 60-120 seconds
Average ramp-up rate (Tsmax to Tp)	3 °C/second max.
Liquidous temperature (TL) Time at liquidous (tL)	217 °C 60-150 seconds
Peak package body temperature (Tp)	255 °C ~260 °C
Classification temperature (Tc)	260 °C
Time (tp) within 5 °C of the specified classification temperature (Tc)	30 seconds
Average ramp-down rate (Tp to Tsmax)	6°C/second max.
Time 25°C to peak temperature	8 minutes max.



Product Packaging Information



ITEM	W	Ao	B ₀	Ko	Р	F	Е	D ₀	D_1	P ₀	P_2	T
DIM	12. 0 +0.30	3. 00 +0.10	4. 20 +0.10 -0.10	4. 55 ^{+0. 10} _{-0. 10}	8.00 +0.10	5. 50 ^{+0. 10} _{-0. 10}	1. 75 +0.10	1. 50 +0. 10 -0. 00	1.00 +0.10 -0.00	4. 00 +0. 10 -0. 10	2. 00 +0. 10 -0. 10	0.40 +0.06
ALTERNATB												



ltem	Quantity	Total	Dimensions(mm)	
Reel	1,700pcs	1,700pcs	R=330	



Cautions

- (1) Moisture monitoring is vital during the storage of LEDs for if too much moisture is absorbed, interface delamination and optical performance degradation will occur. Therefore, products should be packed in moisture-proof aluminum bags so as to reduce moisture absorption to the lowest degree during transportation and storage. Included moisture-proof aluminum bag are the key indicators that they will change from brown to azure if bags are invaded by moisture.
- (2) Soldering process in compliance with the range of the conditions stated above should be conducted after opening the moisture-proof aluminum bag. The rest LEDs should be stored in a hermetically sealed container, silica gel desiccants included. And the original moisture-proof aluminum bags are recommended.
- (3) If the "Period After Opening" storage time is too long or silica gel desiccants don't maintain blue any more, baking process should be done once.



Revision History

Versions	ons Description	
1	Establish a datasheet	2024/01/03

About Edison Opto

Edison Opto is a leading manufacturer of high power LED and a solution provider experienced in LDMS. LDMS is an integrated program derived from the four essential technologies in LED lighting applications- Thermal Management, Electrical Scheme, Mechanical Refinement, Optical Optimization, to provide customer with various LED components and modules. More Information about the company and our products can be found at www.edison-opto.com

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